

INTEGRATED CIRCUIT DEVICE HAVING FLEXIBLE LEADFRAME

Abstract

An integrated circuit device having a flexible leadframe, and techniques for fabricating the flexible leadframe and integrated circuit device, are provided. In one aspect of the invention, an
5 integrated circuit device comprises a heat spreader having a top surface and a bottom surface. At least one integrated circuit die is attached to the top surface of the heat spreader. A flexible leadframe is also attached to the top surface of the heat spreader. The flexible leadframe has one or more flexible layers, including at least one flexible insulating layer. A plurality of electrically conductive traces are defined on the at least one flexible insulating layer.